

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
20V	17mΩ@4.5V	7.6A
	24mΩ@2.5V	

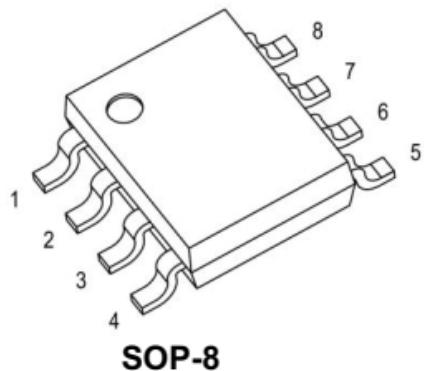
Feature

- TrenchFET Power MOSFET
- Excellent RDS(on) and Low Gate Charge

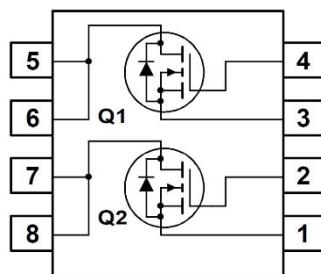
Applications

- Advanced trench process technology
- High density cell design for ultra-low on-resistance
- High power and current handing capability
- Ideal for Lion battery pack applications

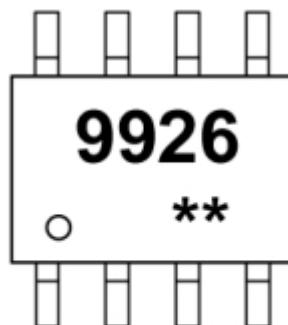
Package



Circuit diagram



Marking



9926 =Device Code
****** =Date Code

Absolute maximum ratings

($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	7.6	A
Pulsed Drain Current ¹⁾	I_{DM}	38	A
Power Dissipation	P_D	2	W
Thermal Resistance from Junction to Ambient ²⁾	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 ~ +150	$^\circ\text{C}$

Electrical characteristics

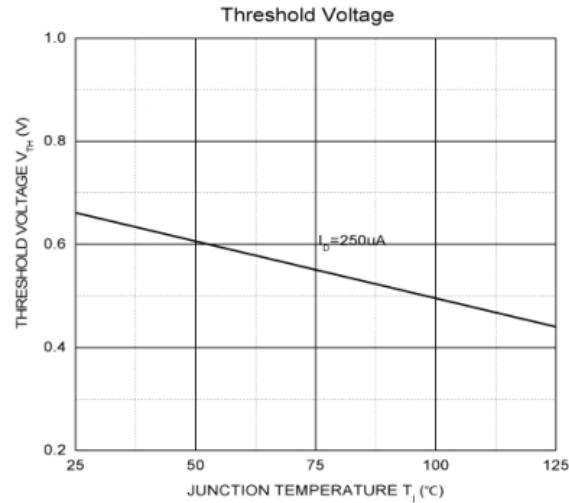
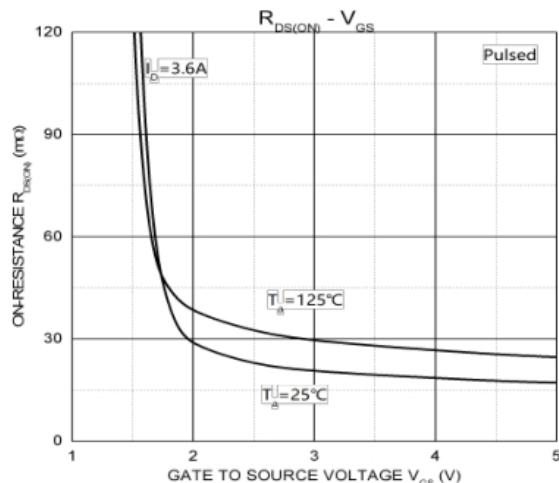
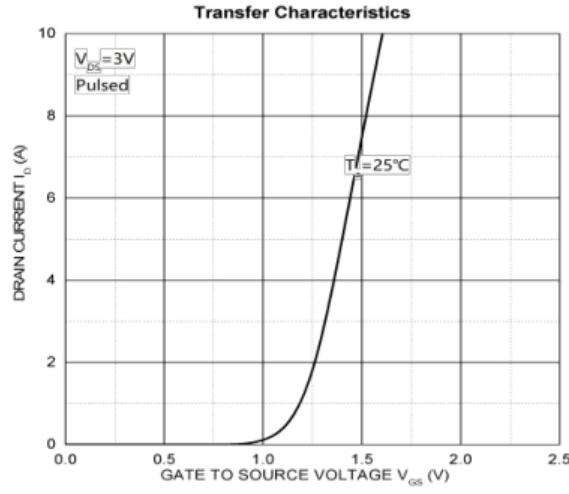
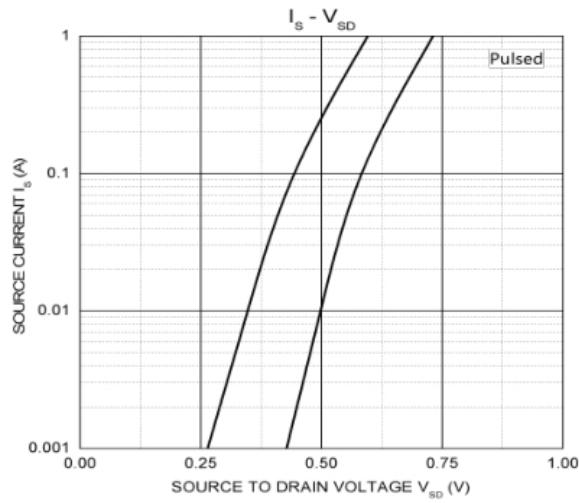
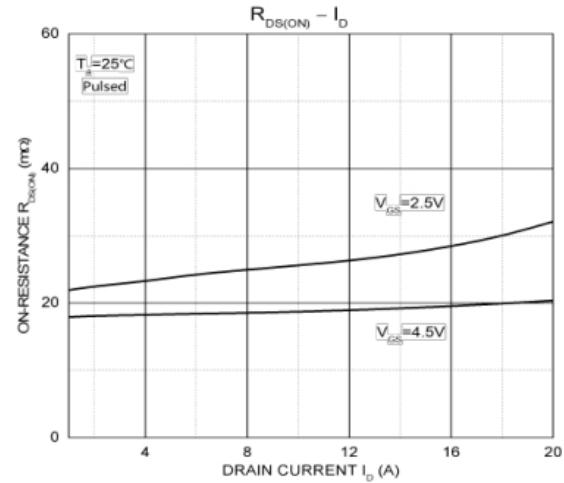
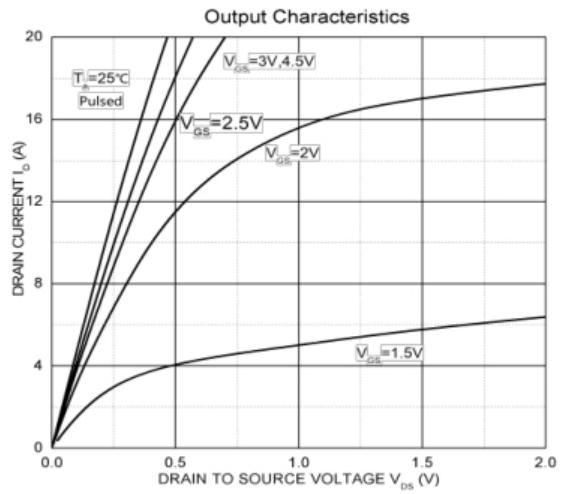
($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-source breakdown voltage	$\text{BV}_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	20			V
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$			1	μA
Gate-body leakage current	I_{GSS}	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$			± 100	μA
Gate threshold voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.45	0.7	1.2	V
Drain-source on-resistance	$R_{DS(\text{on})}$	$V_{GS} = 4.5\text{V}, I_D = 6\text{A}$		17	24	$\text{m}\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 5\text{A}$		24	32	
Dynamic Characteristics						
Input capacitance	C_{iss}	$V_{DS} = 8\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		800		pF
Output capacitance	C_{oss}			155		
Reverse transfer capacitance	C_{rss}			125		
Switching Characteristics						
Turn-on Delay Time	$T_{d(on)}$	$V_{DD} = 10\text{V}, V_{GS} = 4\text{V}, I_D = 1\text{A}, R_{GEN} = 10\Omega$		18		nS
Turn-on Rise Time	T_r			5		
Turn-Off Delay Time	$T_{d(off)}$			43		
Turn-Off Fall Time	t_f			20		
Total Gate Charge	Q_g	$V_{DS} = 10\text{V}, V_{GS} = 4.5\text{V}, I_D = 4\text{A}$		11		nC
Gate-Source Charge	Q_{gs}			2.3		
Gate-Drain Charge	Q_{gd}			2.5		
Source-Drain Diode Characteristics						
Body Diode Voltage ³⁾	V_{SD}	$I_S = 1.7\text{A}, V_{GS} = 0\text{V}$			1.2	V

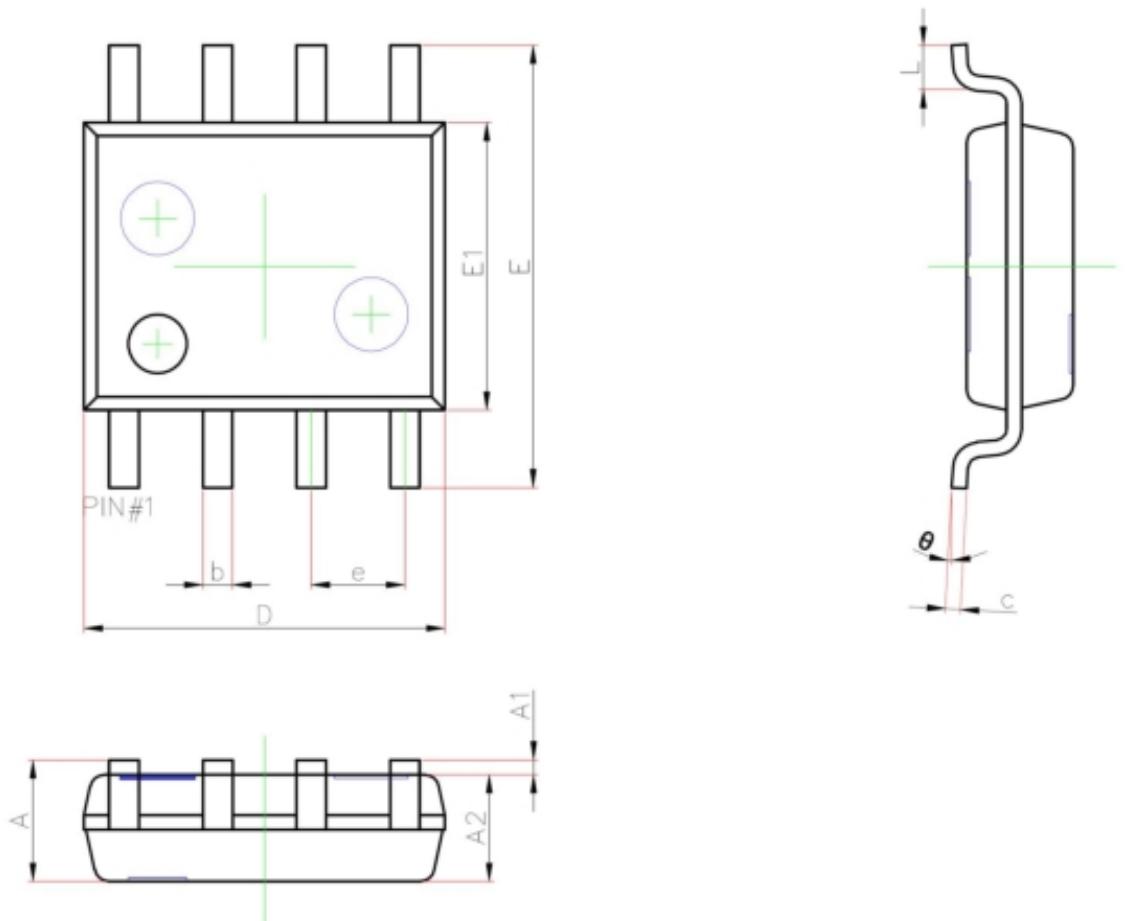
Notes:

1. Repetitive rating: Pulse width limited by junction temperature.
2. Surface mounted on FR4 board, $t \leq 10\text{s}$.
3. Pulse Test: Pulse Width $\leq 80\mu\text{s}$, Duty Cycle $\leq 0.5\%$.
4. Guaranteed by design, not subject to producing.

Typical Characteristics



SOP-8 Package Information



Symbol	Dimensions In Millimeters	
	Min.	Max.
A	1.35	1.75
A1	0.10	0.25
A2	1.35	1.55
b	0.33	0.51
c	0.17	0.25
D	4.80	5.00
e	1.27 REF.	
E	5.80	6.20
E1	3.80	4.00
L	0.40	1.27
θ	0°	8°